



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-10
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32C091RCT6	205W*44DXXXA	A	9991	2024-09-10
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	333	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	10x10	64	Gull wing	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	205W*44DXXXA		332.6390		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.796	mg	supplier	die	Silicon (Si)	7440-21-3		4.640	mg	967430	13949
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	1543	22
				supplier	metallization	Copper (Cu)	7440-50-8		0.066	mg	13828	199
				supplier	metallization	Cobalt (Co)	7440-48-4		0.000	mg	57	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.021	mg	4457	64
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	171	2
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	114	2
				supplier	Passivation	Silicon Nitride	12033-89-5		0.017	mg	3486	50
				supplier	Passivation	Silicon Oxide	7631-86-9		0.043	mg	8914	129
				supplier	Leadframe	Copper (Cu)	7440-50-8		94.300	mg	943000	283490
Leadframe (C7025 + Ag)	Copper & its alloys	100.000	mg	supplier	Leadframe	Nickel (Ni)	7440-02-0		3.200	mg	32000	9620
				supplier	Leadframe	Silicon (Si)	7440-21-3		0.725	mg	7250	2180
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.175	mg	1750	526
				supplier	Leadframe	Silver (Ag)	7440-22-4		1.600	mg	16000	4810
				supplier	Glue or tape	Silver (Ag)	7440-22-4		0.534	mg	755000	1606
Glue epoxy (EN4900G)	Precious metals	0.707	mg	supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.018	mg	25000	53
				supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.060	mg	85000	181
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.039	mg	55000	117
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.007	mg	10000	21
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.039	mg	55000	117
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.004	mg	5000	11
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.004	mg	5000	11
				supplier	Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.004	mg	5000	11
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.006	mg	3500	19
				supplier	Bonding wire	Copper (Cu)	7440-50-8		1.772	mg	965500	5327
Bonding Wire (CuPd)	Precious metals	1.835	mg	supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.057	mg	31000	171
				supplier	Molding Compound	Epoxy Resin A	Proprietary		4.230	mg	20000	12716
				supplier	Molding Compound	Epoxy Resin B	Proprietary		4.230	mg	20000	12716
				supplier	Molding Compound	Phenol Resin	Proprietary		10.575	mg	50000	31791
				supplier	Molding Compound	Carbon Black	1333-86-4		1.163	mg	5500	3497
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	211.500	mg	supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		158.519	mg	749500	476550
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		32.783	mg	155000	98553
				supplier	Molding Compound	Tin (Sn)	7440-31-5		13.799	mg	999928	41483
External Plating (Sn)	M-011 Other inorganic materials	13.800	mg	supplier	Matte Sn	Impurities	Proprietary		0.001	mg	72	3